

IN THE CLAIMS:

Claims 1-51 and 55-62 were previously cancelled. Claims 52 and 53 have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1.-51. (Canceled)

52. (Currently amended) A socket contact formation process for forming a plurality of socket contacts in a substrate, the plurality of socket contacts having a spacing therebetween for mating ~~with the~~ with contacts of an IC chip for use in the testing thereof, comprising:
forming a contact head from a conductive material as at least one member of a socket contact having at least two members forming portions thereof, the contact head for contacting one of the contacts of the IC chip for use in the testing thereof;
forming a contact body from a doped semiconductive material configured to be electrically conductive as a member of a socket contact having at least two members forming portions thereof, the contact body formed from a doped semiconductive material for use in the testing of the IC chip; and
joining the contact head and the contact body forming a socket contact having at least two members forming portions thereof, the joined contact head and the contact body having at least a portion of the contact head contacting at least a portion ~~of a~~ of the contact of the IC chip during the testing thereof.

53. (Currently amended) The process in claim 52, wherein:
forming ~~a contact~~ the contact head comprises stamping a metal element as at least one member of a socket contact having at least two members forming portions thereof;
forming ~~a contact~~ the contact body comprises etching silicon having at least a portion thereof doped to be electrically conductive as at least one member of a socket contact having at least two members forming portions thereof; and
joining the contact head and the contact body further comprises adhering the contact head onto the contact body forming a socket contact having at least two members forming portions thereof.

54. (Previously presented) The process in claim 52, wherein joining the contact head and the contact body further comprises depositing a metal over a doped silicon surface for a socket contact having at least two members forming portions thereof.

55.-62. (Canceled)